

What is claimed is:

1. A semiconductor device test apparatus employed to test one or a plurality of semiconductor devices each provided with a plurality of electrodes, comprising:

a circuit board provided with a circuit corresponding to said semiconductor device and a plurality of electrodes that correspond to individual electrodes at said semiconductor device; and

a connection plate that is provided with a plurality of conductive portions that electrically connect said electrodes at the semiconductor device and said electrodes at said circuit board on a one-to-one basis.

2. A semiconductor device test apparatus according to claim 1, wherein:

said conductive portions are formed at through holes provided at said connection plate.

3. A semiconductor device test apparatus according to claim 1, wherein:

conductive elastic bodies are provided between said connection plate and said semiconductor device to electrically connect said conductive portions at said connection plate and said electrodes at said semiconductor device on a one-to-one basis.

4. A semiconductor device test apparatus according to claim 1, further comprising:

a positioning member that secures said semiconductor device.

5. A semiconductor device test apparatus according to claim 2, further comprising:

a positioning member that secures said semiconductor device.

6. A semiconductor device test apparatus according to claim 3, further comprising:

a positioning member that secures said semiconductor device.

7. A semiconductor device test apparatus according to claim 4 or 5, wherein:

said circuit board, said connection plate and said positioning member are integrated.

8. A semiconductor device test apparatus according to claim 6, wherein:

said circuit board, said connection plate, said conductive elastic bodies and said positioning member are integrated.

9. A semiconductor device test apparatus according to claim 1, further comprising:

a holding member that presses said semiconductor device toward said connection plate.

10. A semiconductor device test apparatus according to claim 9, wherein:

said holding member is provided with a buffer member positioned so as to come in contact with said semiconductor device.

11. A semiconductor device test apparatus according to claim 1, wherein:

said connection plate is constituted of film.

12. A semiconductor device test apparatus according to claim 1, wherein:

said connection plate is constituted of a printed board.

13. A semiconductor device test apparatus according to claim 1, wherein:

said semiconductor device is a chip.

14. A semiconductor device test apparatus according to claim 1, wherein:

said semiconductor device is a wafer.

15. A semiconductor device test apparatus employed to test one or a plurality of semiconductor devices each having a plurality of electrodes, provided with;

a probe holding member with a plurality of probes fitted therein to expose sharp ends thereof and ends thereof on a side opposite from said sharp ends that correspond with individual electrodes at said semiconductor device on a one-to-one basis.

16. A semiconductor device test apparatus according to claim 15, wherein:

at each of said probes, a notched portion is formed in an area located inside said probe holding member.

17. A semiconductor device test apparatus according to claim 15, further provided with:

a plurality of conductive rubber portions that correspond to said probes on a one-to-one basis.

18. A semiconductor device test apparatus according to claim 17, wherein:

a gold-clad film is formed at said probes, at least, in areas where said probes come in contact with said conductive rubber portions.

19. A semiconductor device test apparatus according to claim 15,
wherein:

said semiconductor device is a chip.

20. A semiconductor device test apparatus according to claim 15,
wherein:

said semiconductor device is a wafer.

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